



ACCELERATE[®]HP

APM6-20-01.5-S-04-2-A

APM6-100-01.5-L-04-2-A

APM6 SERIES

(0.635 mm) .025"

HIGH-PERFORMANCE ARRAY TERMINAL

SPECIFICATIONS

Insulator Material:
Black LCP
Contact Material:
Copper Alloy
Plating:
Au or Sn over
50 μ" (1.27 μm) Ni
Operating Temp Range: Testing Now!
Current Rating:
Testing Now
Working Voltage:
Testing Now
RoHS Compliant:
Yes
Lead-Free Solderable:
Yes

Mates with:
APF6

Data rate compatible
with PCIe[®] Gen 5
and 100 GbE

Flexible
open-pin-field

5 mm or 10 mm
stack heights

Four row design
with up to 400 pins

NRZ	PAM4
56	112
Gbps	Gbps

IN DEVELOPMENT

- 6, 8 and 10 rows
- 10, 30, 40, 50, 80 and 90 positions per row

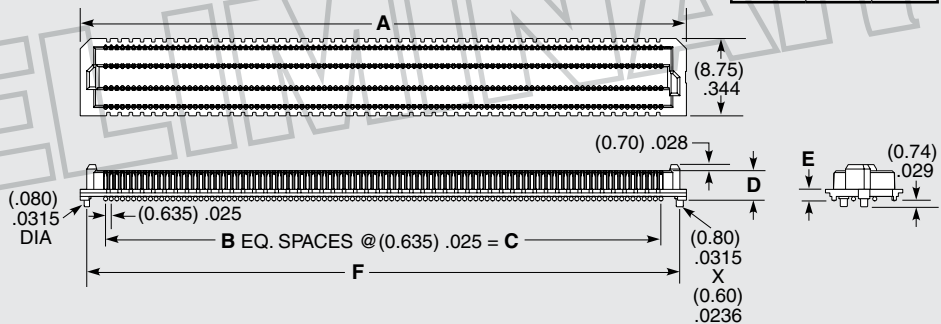
APM6	NO. OF POSITIONS	LEAD STYLE	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	OPTION
	-20, -60, -100 (Per Row)	-01.5 = 1.5 mm -06.5 = 6.5 mm	-L = 10 μ" (0.25 μm) Gold on contact area, Matte Tin on tail -S = 30 μ" (0.76 μm) Gold on contact area, Matte Tin on tail	-04 = Four Rows	-2 = Lead-Free Solder Charge	(Leave blank for no alignment pin) -A = Alignment Pin

NO. OF POSITIONS PER ROW	A	B	C	F
-020	(17.82) .701	19	(12.07) .475	(16.32) .642
-060	(43.22) 1.701	59	(37.47) 1.475	(41.72) 1.642
-100	(68.62) 2.701	99	(62.87) 2.475	(67.12) 2.642

LEAD STYLE	D	E
-01.5	(3.33) .131	(1.23) .048
-06.5	(8.33) .328	(6.23) .245

MATED HEIGHT*		
APF6 LEAD STYLE	APM6 LEAD STYLE	
	-01.5	-06.5
-03.5	(5.00) .197	(10.00) .394

*Processing conditions will affect mated height.



Note:
Some sizes, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

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All parts within this catalog are built to Samtec's specifications.
Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.